

ABSTRACT OF THE DISCLOSURE

A circuit device 10 comprises conductive patterns 11, separated by separation grooves 41, circuit elements 12, affixed onto conductive patterns 11, and an insulating resin 13, covering circuit elements 12 and conductive patterns 11 and filling separation grooves 41 while exposing the rear surfaces of conductive patterns 11. Constricted parts 19 are formed at side surfaces of separation grooves 41. At constricted parts 19, the width of separation grooves 41 is made narrower than at other locations. Thus by making insulating resin 13 adhere closely to constricted parts 19, the adhesion of insulating resin 13 with conductive patterns 11 is improved.